

Product/Process Change Notification PCN07053

Product:	HPL 507	Part Numbers Concerned:	See list attached
Product Manager:	Alan Chen	Issue Date:	27 March, 2007
		Page(s):	2
Distribution:	GLOBAL		

Subject:

Soldering type DDR II and FBDIMM housing enhancement

Background:

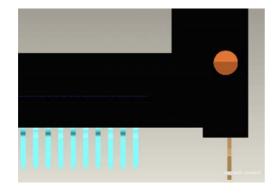
As part of the continuous improvement. FCI is making a change to all Vertical Soldering Type DDR II and FBDIMM housing by adding a rib on the bottom of housing. The connector with this change will be more robust from the housing damage and avoid tin crossing in wave soldering process.

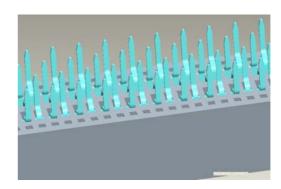
Nature of Change:

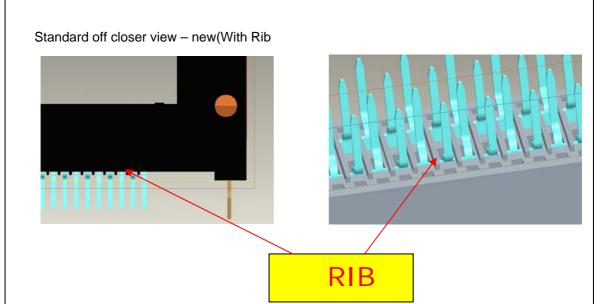
FCI will enhance the housing standoff by adding the rid; refer to the drawing below for detail. After the change the connector will be more robust from the housing damage and avoid tin crossing. There will be a minor change on the outside appearance and no impact to fit & function and customer application as well.

The customer inventory with the current design will be used as before and all the part number will be same as before too.

Standoff closer view(No Rib) - current







Product Lines Affected:

Vertical soldering type DDR II and FBDIMM

Implementation Date:

Running change from June 1, 2007.

Affected Part Numbers:

See attached list

Action Required:

- Sales teams to inform FCI customers for this product change notification.
- FCI Distributors and sub-contractors should notify end customers as required.

For questions regarding this PCN contact:

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Or contact your nearest FCI representative